

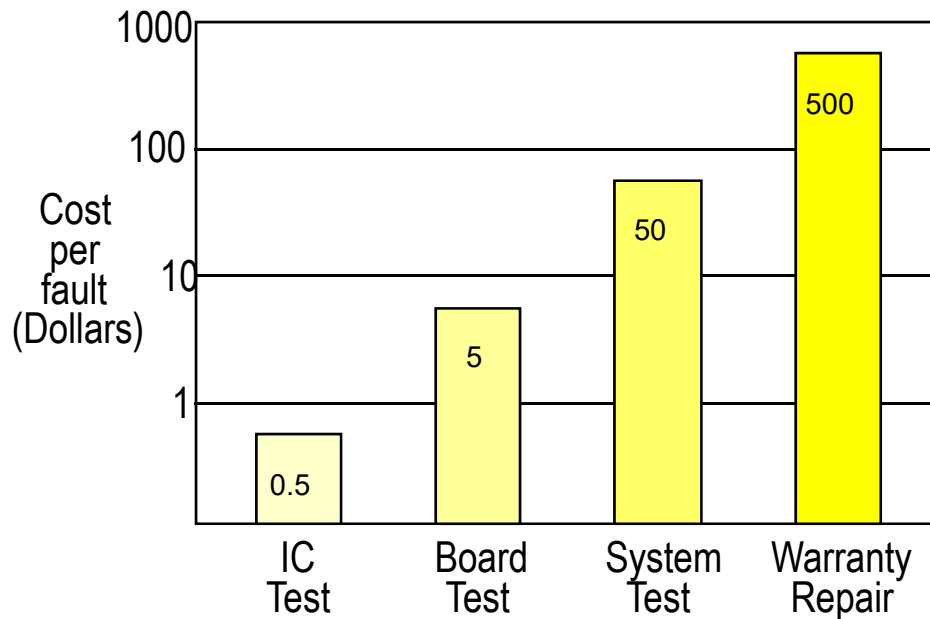
# Introduction

- What Is Testing
- Types of Testing
- Test Quality
- **Test Economics**
  - ♦ **Why and Who Invests in Test?**
    - \* **Global Semiconductor Industry**
  - ♦ **How to Make Optimal Test Decision?**
- Important Research Topics
- Conclusion



# Why Invest in Testing?

- Although testing is expensive
  - ♦ Repair cost is even **more expensive!**
- **Rule of Tens** [Davis 82]



**A Stitch in Time Saves Nine**

# 15% Semiconductor Market Goes to Test

- 2016 global semiconductor market **\$338.9B USD** (WSTS)
  - Packing and test about **15%**
- 2016 Taiwan **\$75.8B USD**, ~**22%** of global market, **World TOP #2**
  - Fabless design \$20.2B USD
  - Manufacture \$41.3B USD
  - Packaging \$10.0B USD
  - Testing \$4.3B USD**

Source IEK, Taiwan

單位：億新台幣

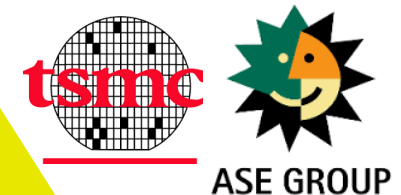
億新台幣	2010 年	2010 年 成長率	2011 年	2011 年 成長率	2012 年	2012 年 成長率	2013 年	2013 年 成長率	2014 年	2014 年 成長率	2015 年	2015 年 成長率	2016 年(e)	2016 年 成長率
IC 產業產值	17,693	38.3%	15,627	-11.7%	16,342	4.6%	18,886	15.6%	22,033	16.7%	22,640	2.8%	23,191	2.4%
IC 設計業	4,548	17.9%	3,856	-15.2%	4,115	6.7%	4,811	16.9%	5,763	19.8%	5,927	2.8%	6,202	4.6%
IC 製造業	8,997	56.0%	7,867	-12.6%	8,292	5.4%	9,965	20.2%	11,731	17.7%	12,300	4.9%	12,459	1.3%
晶圓代工	5,830	42.8%	5,729	-1.7%	6,483	13.2%	7,592	17.1%	9,140	20.4%	10,093	10.4%	10,744	6.5%
記憶體製造	3,167	88.1%	2,138	-32.5%	1,809	-15.4%	2,373	31.2%	2,591	9.2%	2,207	-14.8%	1,715	-22.3%
IC 封裝業	2,870	30.6%	2,696	-6.1%	2,720	0.9%	2,844	4.6%	3,160	11.1%	3,099	-1.9%	3,170	2.3%
IC 測試業	1,278	32.3%	1,208	-5.5%	1,215	0.6%	1,266	4.2%	1,379	8.9%	1,314	-4.7%	1,360	3.5%
IC 產品產值	7,715	39.2%	5,994	-22.3%	5,924	-1.2%	7,184	21.3%	8,354	16.3%	8,134	-2.6%	7,917	-2.7%
全球半導體成長率	-	31.8%	-	0.4%	-	-2.7%	-	4.8%	-	9.9%	-	-0.2%	-	1.7%

# Many Companies Invest Heavily in Test

**IDM**



**Fabless/Foundry**



**EDA**

ATPG  
Fault Sim.

**Design**

BIST, DFT  
Boundary Scan

**Manufacture**

Fabrication, Assembly, Test  
Physical Failure analysis

# World's Top EDA Companies

- 2016 global EDA market is about **\$8B USD**
  - ♦ Growing 5~9% each year

Company	Rank	Revenue	Country
Synopsys	1	\$2.42 B	USA
Cadence	2	\$1.82 B	USA
Mentor Graphics (now Siemens)	3	\$1.18 B	Europe



cā d e n c e<sup>TM</sup>

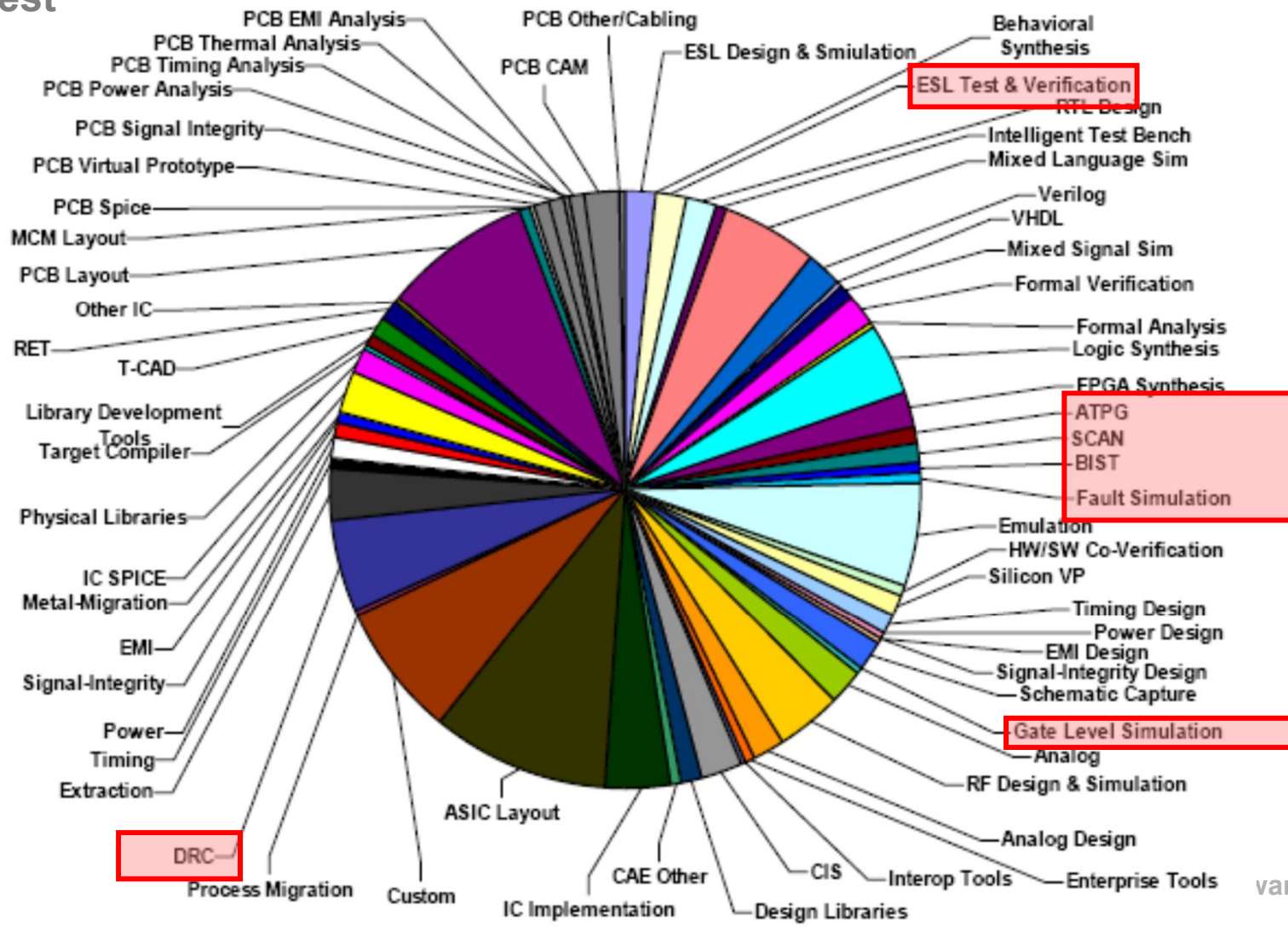




# EDA Market by Tool

- Test-related tools are about 5~10% EDA revenue

dataquest  
2012



# World's Top OSAT Companies

- **OSAT** = outsourced semiconductor assembly and test
- About 1/3 IC tested by Taiwan

Gartner, 2015

Company	Rank	Market	Country
日月光 ASE	1	18.7%	Taiwan
艾克爾 Amkor	2	11.3%	USA
矽品 SPIL	3	10.2%	Taiwan
長電科技 JCET	4	6.6%	China
力成 PTI	5	5.2%	Taiwan



**Test Important for IC Industry**

# Introduction

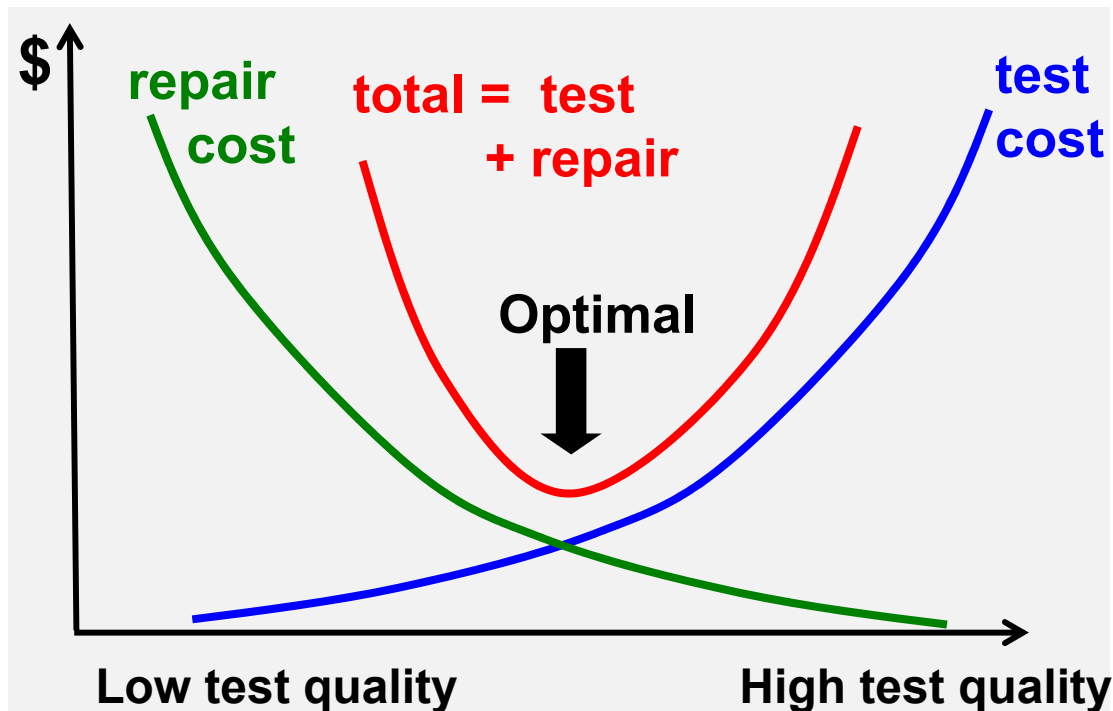
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# How to Make Optimal Decision?

- Optimal test not only **technical** issue, but also **economics** issue
  - ♦ Trade off between **test cost** and **repair cost**
- Different product has different optimal decision
  - ♦ **No single best decision** for all products!



# What Cost Can We Optimize?

- **EDA:** ATPG, fault simulator ...
  - ◆ Typically **10K ~ 100K USD**
- **Design:** insert DFT/BIST circuitry
  - ◆ Area/power/delay overhead about **5~10%**
- **OSAT:**
  - ◆ Equipment
    - \* Tester (Automatic Testing Equipment, ATE)
      - Typically **0.5~3 M USD**
    - \* Handler, probe station, Burn-in oven
  - ◆ Test application time (TAT)
    - \* Around **\$50 to \$300 USD** per hour
    - \* ASIC takes **2~3** seconds. CPU can be **0.5~1** minute
  - ◆ load board, probe card
    - \* **\$1K ~ 20K USD**

**Many Decisions to Make**

# Case 1: DFT or Not?

Q1: Without DFT

Y=98%, FC=70%. DL=?

$$DL = 1 - Y^{(1-FC)}$$

A: 6,043 DPM

Q2: With DFT

Y=97%, FC=99%. DL=?

A: 304 DPM

**Technically, DFT Improves DPM**  
**Economically, Is DFT Worth Doing?**

# Case 1: DFT or Not? (Cont'd)

- Q: Is it economical to insert DFT?
- A: Yes. This is true for many products.

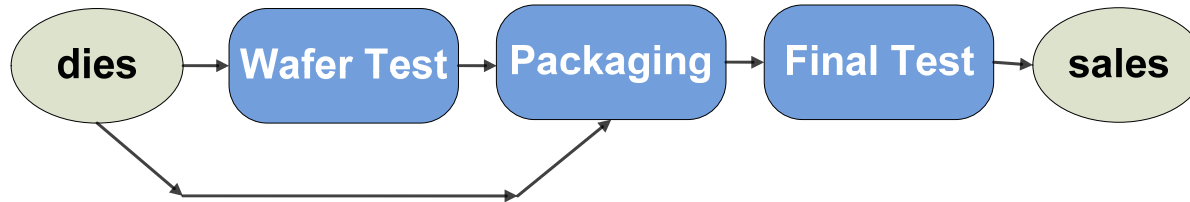
$$DL = 1 - Y^{(1-FC)}$$

- ♦ Although Y drops, DL improves significantly

Item	w/o DFT	with DFT
Total # of Dies	1,000,000	900,000
Yield	98%	97%
FC fault coverage	70%	99%
$DL = 1 - Y^{(1-FC)}$	6,043 DPM	304 DPM
Sales = $D \times Y \times \$1$	980,000	873,000
Repair cost = $D \times Y \times DL \times \$100$	592,163	26,587
Profit = $S - R$	387,837	846,413

**DFT Is Worth Doing!**

# Case 2: Wafer Test or Not?



Item	bad yield = 64%		good yield = 81%	
	with WT	no WT	with WT	no WT
Total # of Dies	1,000,000	1,000,000	1,000,000	1,000,000
$C_{WT} = D \times \$0.02$	20,000	0	20,000	0
$Y_{WT}$	80%	100%	90%	100%
$C_{PK} = D \times Y_{WT} \times \$0.1$	80,000	100,000	90,000	100,000
$C_{FT} = D \times Y_{WT} \times \$0.06$	48,000	60,000	54,000	60,000
$Y_{FT}$	80%	64%	90%	81%
$Sales = D \times Y_{WT} \times Y_{FT} \times \$1$	640,000	640,000	810,000	810,000
$Cost = C_{WT} + C_{PK} + C_{FT}$	148,000	160,000	164,000	160,000
$Profit = S - C$	492,000	480,000	646,000	650,000

**WT or not Depends on Yield**

# Case 3: To Burn or Not To Burn?

Q: Is it worth doing burn-in (BI)?

BI cost is \$2 per die. BI improves quality by 1,000DPM.

Fabrication cost is 30% of price. Repair cost is 30 times price.

Item	ASIC, Price per die= \$10		CPU, Price per die= \$100	
	with BI	no BI	with BI	no BI
$D_F$ = # of Dies fab	1,000,000	1,000,000	1,000,000	1,000,000
$D_S$ = # of dies sold	999,000	1,000,000	999,000	1,000,000
$D_B$ = # of bad dies sold	0	1,000	0	1,000
Sales = $D_S \times P$	9,990,000	10,000,000	99,900,000	100,000,000
$C_{FB} = D_F \times P \times 30\%$	3,000,000	3,000,000	30,000,000	30,000,000
$C_{BI} = D_F \times \$2$	2,000,000	0	2,000,000	0
$C_{RP} = D_B \times P \times 30$	0	300,000	0	3,000,000
Profit = $S - C_{FB} - C_{BI} - C_{RP}$	4,990,000	6,700,000	?	?

**BI or not Depends on Price**

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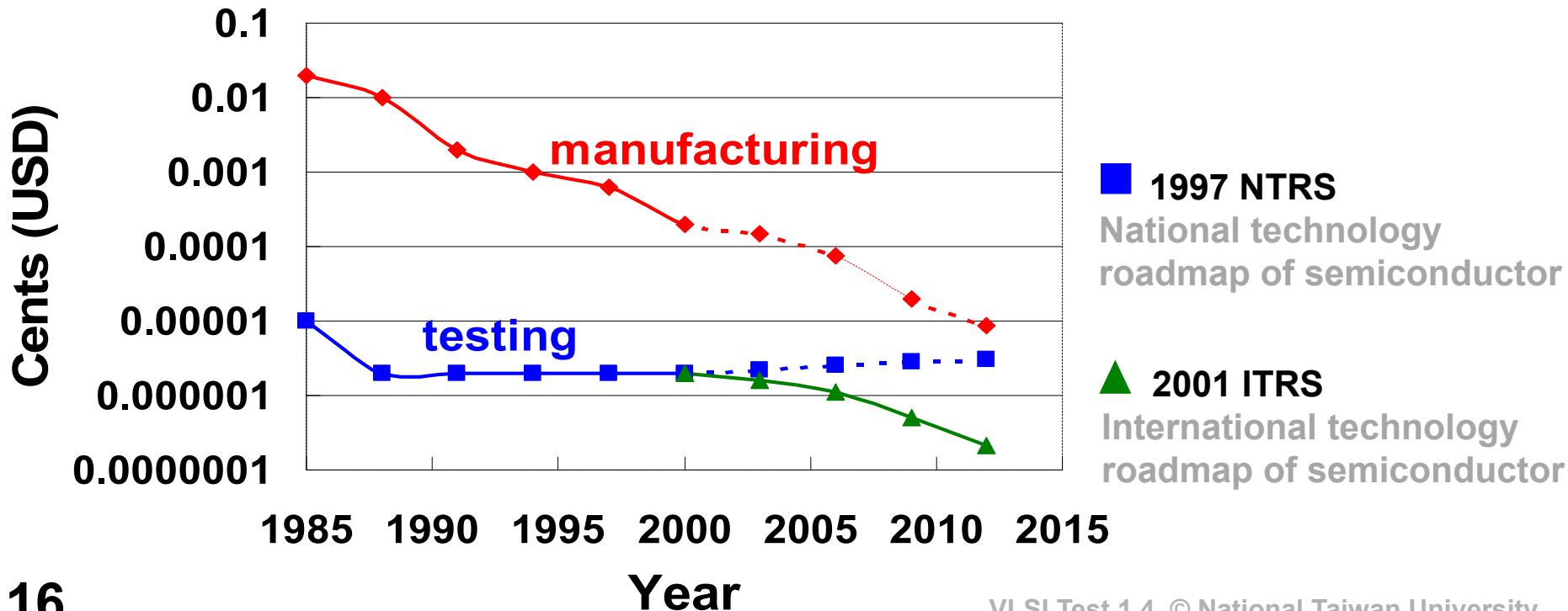




# Test Needs Continuing Improvements

- **NTRS 1997** predicted test cost will be greater than manufacturing cost
  - ♦ assume that historical trends continued
- **ITRS 2001** revised the prediction
  - ♦ Significant research efforts applied to push test cost down

## Cost per Transistor



# Important Research Topics

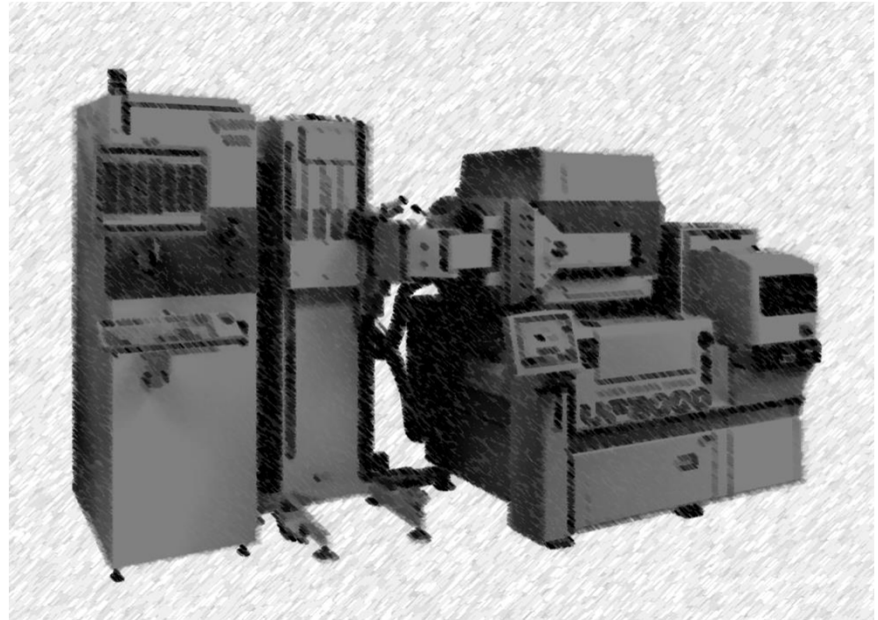
- **Reduce test cost**
  - ◆ Reduce test equipment cost
    - \* *Built-in Self Test (BIST)*
  - ◆ Reduce test data volume, test application time
    - \* *Test compression, ATPG, Memory tests*
- **Improve test quality**
  - ◆ Better *fault models, delay tests*
  - ◆ *Design for testability (DFT)*
- **Improve yield**
  - ◆ *Diagnosis*
- **Better/faster EDA tools**
  - ◆ ATPG, Fault simulator, optimization algorithms

# Major Conferences and Journals

- International Conferences
  - ◆ IEEE Int'l Test Conference (**ITC**)
  - ◆ IEEE/ACM Design Automation Conference (**DAC**)
  - ◆ IEEE VLSI Test Symposium (**VTs**)
  - ◆ IEEE Asian Test Symposium (**ATS**)
  - ◆ IEEE European Test Symposium (**ETS**)
  - ◆ IEEE Design and Test in Europe (**DATE**)
  - ◆ IEEE Int'l Conference on CAD (**ICCAD**)
- Journals
  - ◆ IEEE Trans. On Computer-Aided Design (**TCAD**)
  - ◆ IEEE Trans. On VLSI Systems (**TVLSI**)
  - ◆ IEEE Trans. On Computers (**TC**)
  - ◆ ACM Trans. On Design Auto. of Electronic Systems (**TODAES**)
  - ◆ Journal of Electronic Testing : Theory and Application (**JETTA**)
- IEEE Design & Test Magazine (**D&T**)

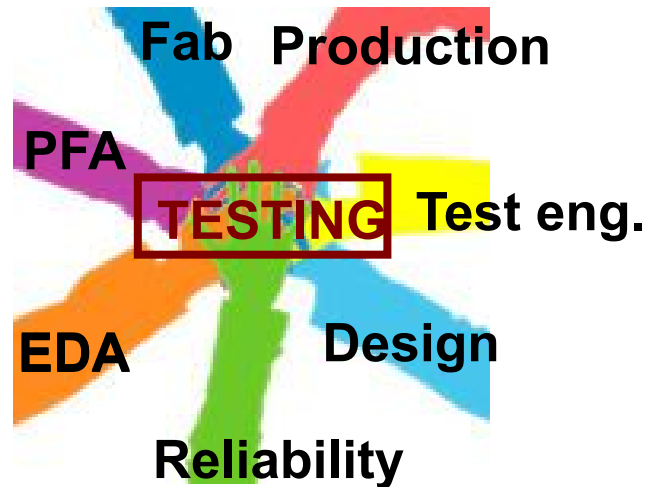
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# Conclusion

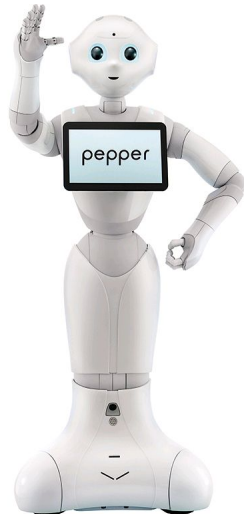
- WHY test?
  - ◆ It is **important to invest** in test because of **rule of ten**
- HOW to test?
  - ◆ Optimal test not only **technical issue**, but also **economics issue**
  - ◆ **No single best test solution for all products!**
- WHO responsible?
  - ◆ Testing is joint responsibility of **everybody**



# Without Testing, It Is a Gamble!



**Testing Does, and Also Will,  
Play Very Important Role  
in High-tech Industry.**



# References

- **[Agrawal 82] V. D. Agrawal, S. C. Seth, P. Agrawal, “Fault Coverage Requirement in Production Testing of LSI Circuits,” IEEE J. Solid-State Circuits, vol. SC-17, no. 1, pp. 57-61, Feb. 1982.**
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- **[McCluskey 88] E.J. McCluskey ; F. Buelow, “IC quality and test transparency,” Int’l Test Conf., 1988.**
- **[Williams 81] T. W. Williams, N. C. Brown, “Defect Level as a Function of Fault Coverage,” IEEE Trans. on Computers, vol. C-30, no. 12, pp. 987-988, Dec.1981.**